



SF2037B-2

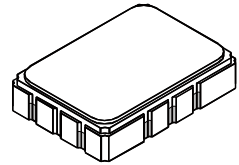
**76.500 MHz
SAW Filter**

- **Designed for SDARS IF Receiver**
- **Low Insertion Loss**
- **5.0 X 7.0 mm Surface-Mount Case**
- **Differential or Single Ended Input and Output**
- **Complies with Directive 2002/95/EC (RoHS)**



Absolute Maximum Ratings

Rating	Value	Units
Maximum Incident Power in Passband	+10	dBm
Max. DC voltage between any 2 terminals	30	VDC
Storage Temperature Range (with tape & reel)	-40 to +85	°C
Storage Temperature Range (without tape & reel)	-50 to +125	°C
Max Soldering Profile	265°C for 10 s	



SMP-03

Electrical Characteristics

Characteristic	Sym	Notes	Min	Typ	Max	Units
Nominal Center Frequency	f_c	1		76.500		MHz
Passband	Insertion Loss IL	1		10.0	12.5	dB
	1dB Passband BW_1		3.8	4.1		MHz
	15dB Bandwidth BW_{15}			6.7	6.8	MHz
	30dB Bandwidth BW_{30}			7.7	7.8	MHz
	Amplitude Ripple over $f_c \pm 1.9$ MHz				0.5	1.10
	Group Delay Variation over $f_c \pm 1.9$ MHz	GDV		65	150	ns _{p-p}
Rejection	50 to 70.44 MHz	1, 3	37	43		dB
	70.44 to 72.04 MHz		34	43		
	81.26 to 82.56 MHz		38	49		
	82.56 to 86.50 MHz		39	48		
	86.5 to 91.50 MHz		41	48		
	91.50 to 100.000 MHz		45	58		
Operating Temperature Range	T_A	1	-40		+105	°C
Frequency Temperature Coefficient	FTC			-18		ppm/°C
Differential Input			175 ohms			
Differential Output			1000 ohms			
Case Style		6	SMP-03 7 x 5 mm Nominal Footprint			
Lid Symbolization (YY=year, WW=week, S=shift) See note 4			RFM SF2037B-2 YYWWS			

Electrical Connections

Connection	Terminals
Port 1 Hot	10
Port 1 Ground Return	1
Port 2 Hot	5
Port 2 Ground Return	6
Case Ground	All Others

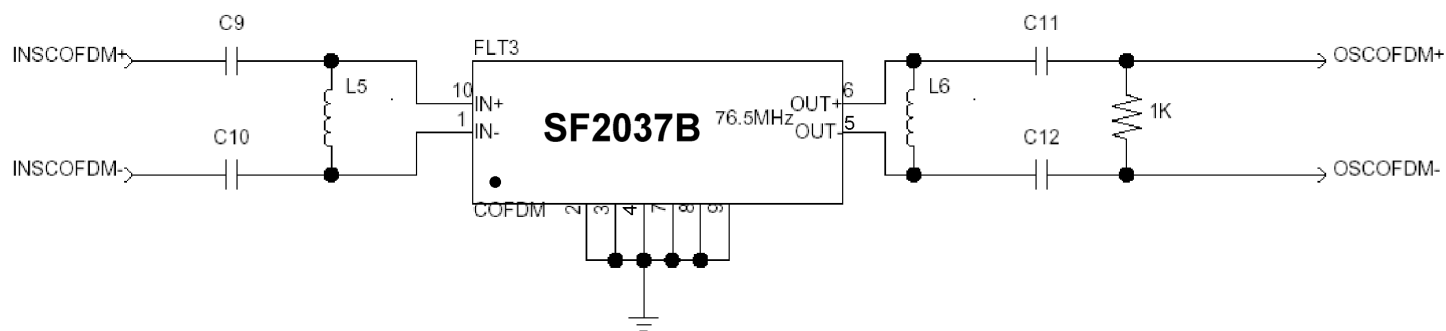
Notes:

1. Unless noted otherwise, all specifications apply over the operating temperature range with filter soldered to the specified demonstration board with impedance matching to 50 Ω and measured with 50 Ω network analyzer.
2. Unless noted otherwise, all frequency specifications are referenced to the nominal center frequency, f_c .
3. Rejection is measured as attenuation below the minimum IL point in the passband. Rejection in final user application is dependent on PCB layout and external impedance matching design. See Application Note No. 42 for details.
4. "LRIP" or "L" after the part number indicates "low rate initial production" and "ENG" or "E" indicates "engineering prototypes."
5. The design, manufacturing process, and specifications of this filter are subject to change.
6. Tape and Reel Standard ANSI / EIA 481.
7. Either Port 1 or Port 2 may be used for either input or output in the design. However, impedances and impedance matching may vary between Port 1 and Port 2, so that the filter must always be installed in one direction per the circuit design.
8. US and international patents may apply.
9. RFM, stylized RFM logo, and RF Monolithics, Inc. are registered trademarks of RF Monolithics, Inc.
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11. Electrostatic Sensitive Device. Observe precautions for handling.



Matching Circuit and Matching Component Values Used in G3 Sirius Radios

(Refer to Sirius Radio G3 Chipset Application Note, Doc. #RX000104-B, Sec. 4.2.4)

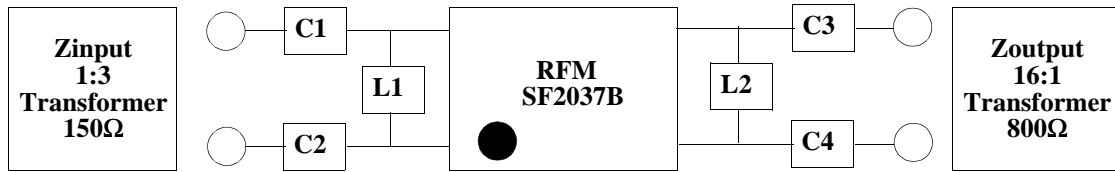


COFDM Narrowband SAW Matching Circuit

COFDM Narrowband SAW Matching Values

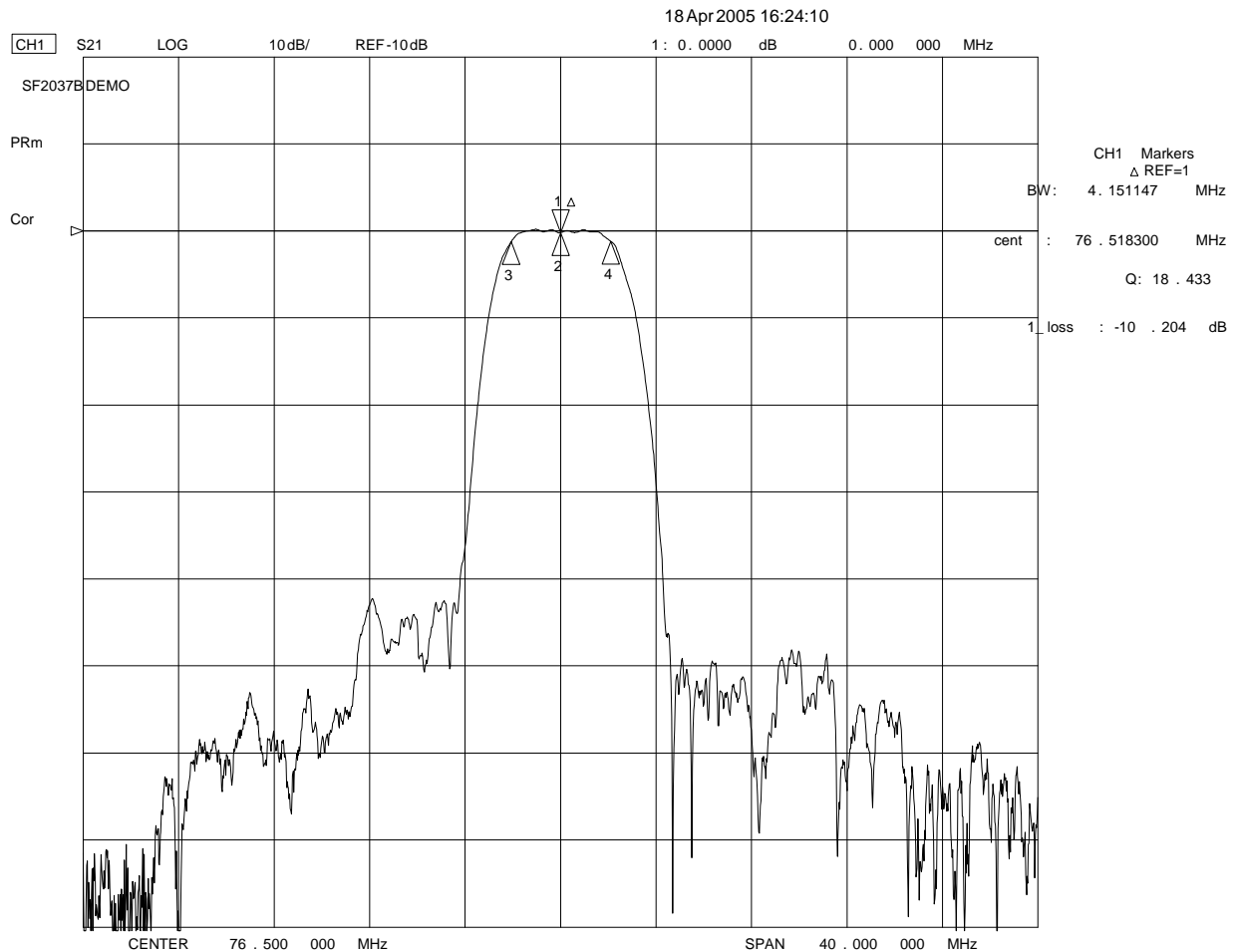
Reference Designator	Value
C9	10 pF
C10	10 pF
L5	270 nH
L6	390 nH
C11	100 pF
C12	100 pF

Matching Circuit and Matching Component Values Used on Filter Demo Board

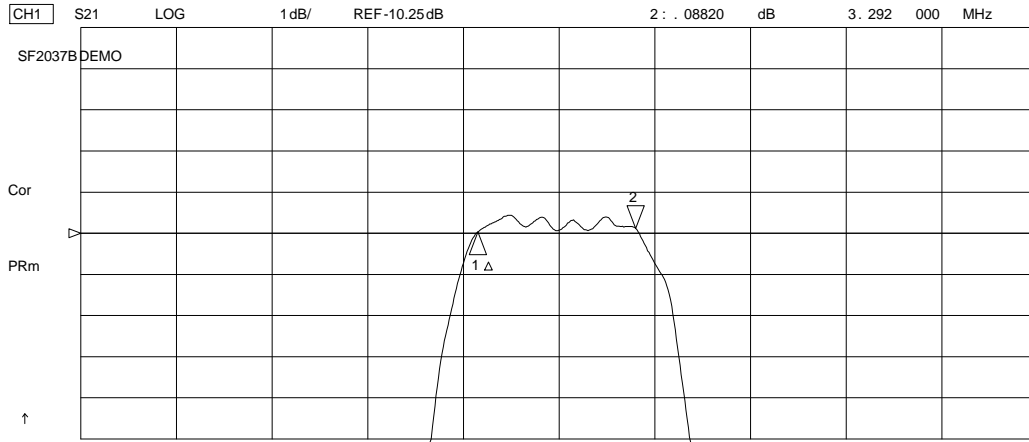


SF2037B
76.500 MHz

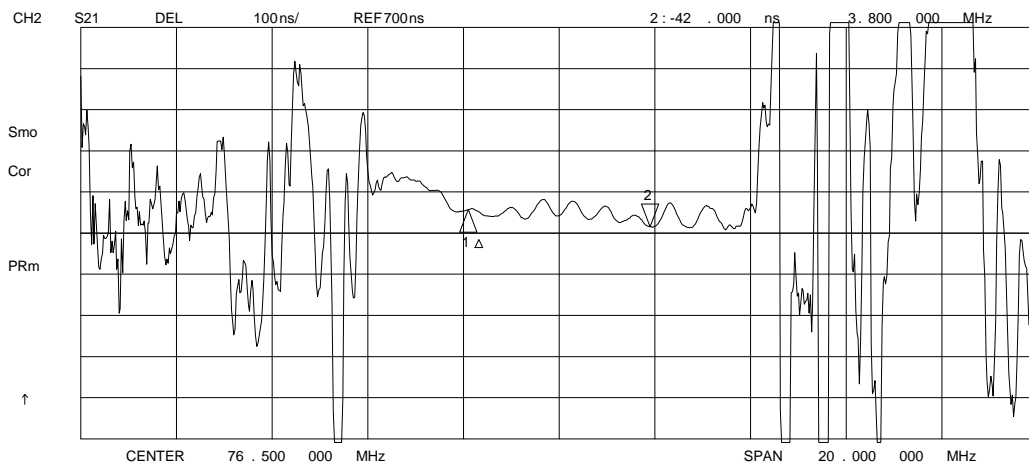
C1 = 9pF
C2 = 9pF
L1 = 270nH
L2 = 330nH
C3 = 18pF
C4 = 18pF



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CH1 Markers
Δ REF=1
mean : -10 .015 dB
s. dev : .10870 dB
p-p : .41040 dB



CH2 Markers
Δ REF=1
mean : 748 .87 ns
s. dev : 14 .984 ns
p-p : 65 .994 ns

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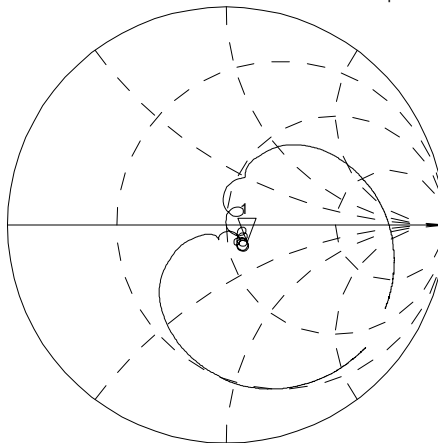
CH1 S11 1UFS

1: 59.928 Ω -9.8086 Ω 212.11 pF 76.500 000 MHz

SF2037BDEMO

Cor

PRm

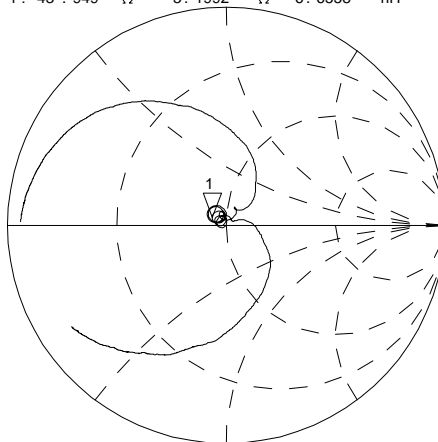


CH2 S22 1UFS

1: 43.949 Ω 3.1992 Ω 6.6558 nH 76.500 000 MHz

Cor

PRm

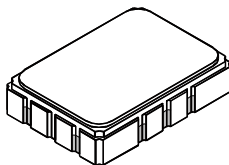


CENTER 76.500 000 MHz

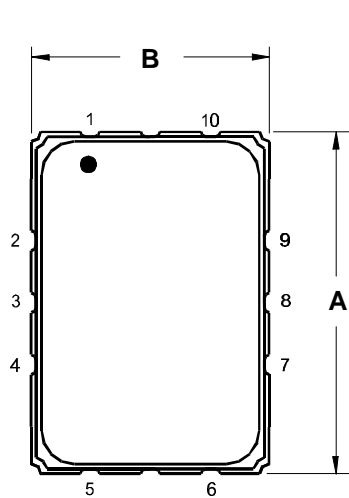
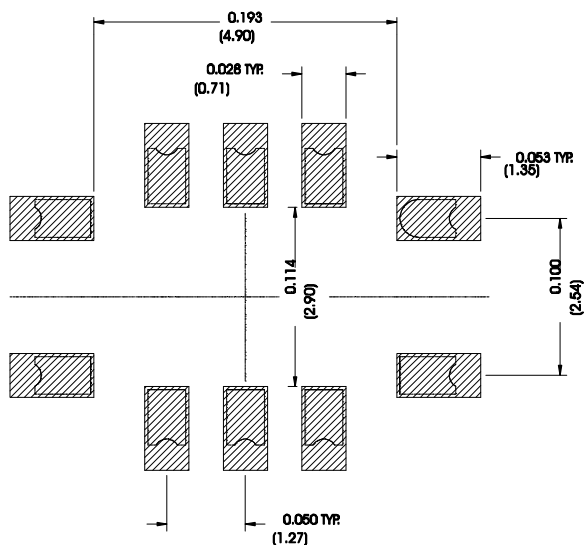
SPAN 40.000 000 MHz

SMP-03 Case

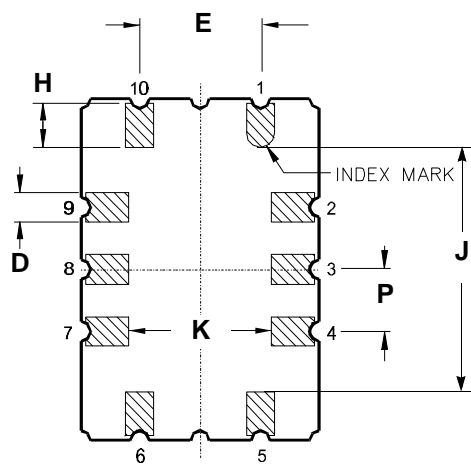
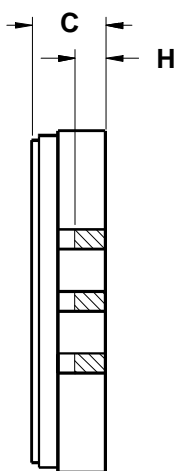
10-Terminal Ceramic Surface-Mount Case 7 x 5 mm Nominal Footprint



Recommended PCB Footprint



TOP VIEW



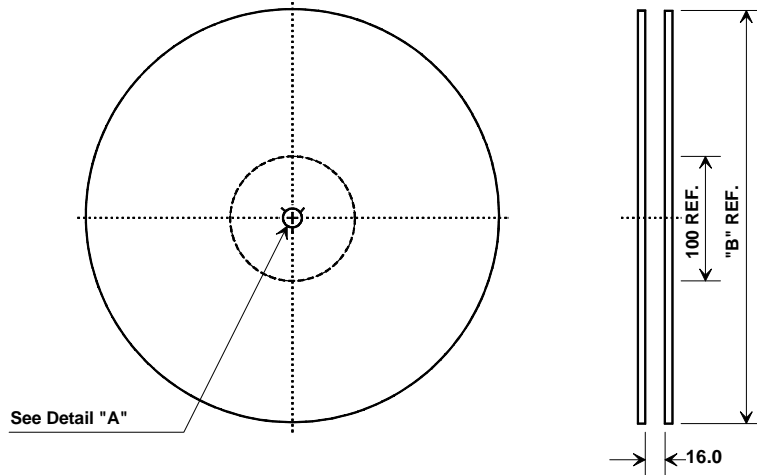
BOTTOM VIEW

Case Dimensions						
Dimension	mm			Inches		
	Min	Nom	Max	Min	Nom	Max
A	6.80	7.00	7.20	0.268	0.276	0.283
B	4.80	5.00	5.20	0.189	0.197	0.205
C		1.65	2.00		0.065	0.079
D	.47	0.60	.73	0.019	0.024	0.029
E	2.41	2.54	2.67	0.095	0.100	0.105
H	0.87	1.0	1.13	0.034	0.039	0.044
J	4.87	5.00	5.13	0.192	0.197	0.202
K	2.87	3.00	3.13	0.113	0.118	0.123
P	1.14	1.27	1.40	0.045	0.050	0.055

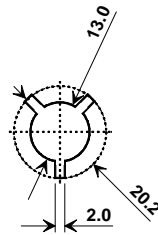
Materials	
Solder Pad Termination	Au plating 30 - 60 ulnches (76.2-152 uM) over 80-200 ulnches (203-508 uM) Ni.
Lid	Fe-Ni-Co Alloy Electroless Nickel Plate (8-11% Phosphorus) 100-200 ulnches Thick
Body	Al ₂ O ₃ Ceramic
Pb Free	

Electrical Connections		
Connection		Terminals
Port 1	Input or Return	10
	Return or Input	1
Port 2	Output or Return	5
	Return or Output	6
Ground		All others
Single Ended Operation		Return is ground
Differential Operation		Return is hot

Tape and Reel Specifications



"B "		Quantity Per Reel
Inches	millimeters	
7	178	500
13	330	2000



COMPONENT ORIENTATION and DIMENSIONS

Carrier Tape Dimensions	
Ao	5.5 mm
Bo	7.5 mm
Ko	2.0 mm
Pitch	8.0 mm
W	16.0 mm

